

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6893807

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOUNGJAE SON	08/05/2021
GUESUK LEE	08/05/2021
TAEMIN EARMME	08/05/2021
HYEONGYUN LEE	08/05/2021
SEUNGCHUL HAN	08/05/2021
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17408437
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	pto@muirpatentlaw.com
Correspondent Name:	MUIR PATENT LAW, PLLC
Address Line 1:	P.O. BOX 1213
Address Line 4:	GREAT FALLS, VIRGINIA 22066
ATTORNEY DOCKET NUMBER:	SAM-59193
NAME OF SUBMITTER:	SANG KI HWANG
SIGNATURE:	/Sang Ki Hwang/
DATE SIGNED:	08/31/2021
Total Attachments: 4	
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**COMBINED DECLARATION (37 CFR § 1.63) FOR UTILITY PATENT APPLICATION AND
ASSIGNMENT FORM¹**

The undersigned acknowledges that this document is being used both as an assignment of the invention and as the declaration (37 CFR § 1.63) for a Utility or Design Application.

WHEREAS, the undersigned, hereinafter referred to individually and collectively as Assignor, has invented:

Title: **CHUCK ASSEMBLY, SEMICONDUCTOR DEVICE FABRICATING APPARATUS
INCLUDING THE SAME, AND METHOD OF FABRICATING SEMICONDUCTOR DEVICE**

for which Assignor is about to make or has made United States or International application for patent.

WHEREAS, as a below named inventor(s), I/(we) hereby declare that:

Section I. Declaration

This declaration is directed to:

- ☒ The attached U.S. non-provisional patent application, or
- ☐ U.S. non-provisional patent application number _____,
filed on _____, or
- ☐ PCT international patent application number _____,
filed on _____.

The above-identified application was made or authorized to be made by me (us).

I (we) believe that I am (we are) the original inventor (original joint inventors) of a claimed invention in the above-identified application.

I (we) hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified application, including the claims.

I (we) acknowledge that I (we) am (are) aware of the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56.

¹ This form requires the use of an Application Data Sheet.

SEC Ref No. IE-202010-031-1-US0 Attorney Ref No. SAM-59193

Section II. Assignment

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, the undersigned hereby sell(s) and assign(s) to

Samsung Electronics Co., Ltd.

having an address at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 U.S.C. § 100, in the invention described in the application identified in Section I of this document.

Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

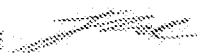
Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or other similar right to Assignee.

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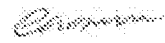
SAMSUNG ELECTRONICS CO., LTD.

The undersigned hereby grant(s) the law firm of Muir Patent Law, PLLC the power to insert on this Declaration and Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

Section III. Inventor(s)/Assignor(s) Signature(s)

LEGAL NAME OF FIRST INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	SON	Youngjae	
SIGNATURE  DATE 21. 8/5			

LEGAL NAME OF SECOND INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	LEE	Guesuk	
SIGNATURE  DATE 21. 8/5			

LEGAL NAME OF THIRD INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	EARMME	TAEMIN	
SIGNATURE  DATE 21/8/5			

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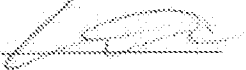
COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM

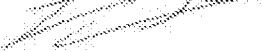
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SAMSUNG ELECTRONICS CO., LTD.

LEGAL NAME OF FOURTH INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	LEE	HYEONGYUN	

SIGNATURE		DATE	2021.08.05
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LEGAL NAME OF FIFTH INVENTOR/ASSIGNOR	Family Name HAN	First Given Name SEUNGCHUL	Second Given Name
SIGNATURE  DATE 2004.08.05			

SEC Ref No. IE-202010-031-1-USO Attorney Ref No. SAM-59193

COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM

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RECORDED: 08/31/2021

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